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GE Energy

**Functional Testing Specification**

*Parts & Repair Services  
Louisville, KY*

**LOU-GED-DS3800HPRB**

**Test Procedure for a HPRB card.**

**DOCUMENT REVISION STATUS:** Determined by the last entry in the "REV" and "DATE" column

REV.	DESCRIPTION	SIGNATURE	REV. DATE
A	Initial release. Transferred information from Salem test to Louisville format. Add adjustment on pot R62	E. Rouse	05/27/2011
B			
C			

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<p><b>LOU-GED-DS3800HPRB REV. A</b></p>	<p><b>g</b></p> <p><b>GE Energy</b> Parts &amp; Repair Services Louisville, KY</p>	<p><b>Page 2 of 3</b></p>
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## Functional test procedure for a DS3800HPRB Card

### 1. SCOPE

1.1 This is a functional testing procedure for a Card.

### 2. STANDARDS OF QUALITY

2.1 Refer to the current revision of the IPC-A-610 standard for workmanship standards.

### 3. APPLICABLE DOCUMENTS

3.1 The following document(s) shall form part of this specification to the extent specified herein. Unless otherwise indicated, the latest issue shall apply.

3.1.1 Check board's electronic folder for more information

### 4. ENGINEERING REQUIREMENTS

#### 4.1 Equipment Cleaning

4.1.1 Equipment should be clean and free of debris prior to applying power unless performing an initial check. Refer to site specific SRA's for cleaning guidelines.

#### 4.2 Equipment Inspection

4.2.1 Equipment should be visually inspected for any defects prior to applying power. This inspection should include the following as a minimum:

4.2.1.1 Wires broken or cracked

4.2.1.2 Terminal strips / connectors broken or cracked

4.2.1.3 Loose wires

4.2.1.4 Components visually damaged

4.2.1.5 Capacitors leaking

4.2.1.6 Solder joints damaged or cold

4.2.1.7 Circuit board burned or de-laminated

4.2.1.8 Printed wire runs burned or damaged

### 5. EQUIPMENT REQUIRED

5.1 The following equipment is required to perform the process requirements. Equipment may be substituted provided that all accuracy's and test ratios are equivalent or better.

Qty	Reference #	Description
1		FVMA Tester
1		Signal Generator HP 3324A or equivalent
1		Fluke 85 Multimeter or equivalent
1		Pot Sealant

## 6. TESTING PROCESS

### 6.1 Testing Procedure

**6.1.1** When Testing this card, the system may need resetting (Red Button) Several Times

**6.1.2** Set Jumpers to the following configuration

J0=1	J1=1	J3=1	J4=1	J5(9)=F	J6(C)=T
J7(D)=T	J8(A)=F	J9(B)=F	J10(8)=F	J11(SB)=MPU	J12(SA)=MPU

**6.1.3** Place the board under test in slot 2K

**6.1.4** Turn on the DC power supply

**6.1.5** Set the instruments; Hewlett Packard – Sweep Generator – 3324A or equivalent.

**6.1.6** Connect cable #305A4207G2 from the output of the sweep generator to HPRB (JA).

**6.1.7** Apply 10Khz 30V P to P square wave.

**6.1.8** Check for 0VDC +/- 0.1V at test-point MTP1 to ACOM. Keep meter attached.

**6.1.9** Execute the HPRB test.

**6.1.10** Make sure voltage at MTP1 goes to 9.65VDC +/- 0.05. Adjust pot R62 if not. Once proper voltage is stable, seal pot.

**6.1.11** Verify that the frequency on all four channels is 10Khz, +/- 0.01Khz. The display should read; U22 = 10.00, U23 = 10.00, U24 = 10.00, U25 = 10.00. These readings may vary from 9.98 to 10.02.

**6.1.12** When installing this card it could shut down the system, when power is cycled the system should reboot.

**6.2 \*\*\*TEST COMPLETE \*\*\***

## 7. NOTES

**7.1** None at this time.